



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

**RESPONSE TO JULY 18, 2001 OFFICE ACTION**

To: Box Fee Amendment  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.  
(Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3828

Responsive to the Office Action dated July 18, 2001, Applicant amends  
and remarks as follows:

**AMENDMENTS**

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